IPC ASSOCIATION CONNECTED ELECTRONICS INDUST.	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			Dec Cla	s/No, Homogeneous Mater	ials and Mfg Information					
upplier Info	rmation											
Company name* Company			npany unique ID	y unique ID U		Unique ID Authority			Response Date*			
nsemi							2025-06-07					
Contact Name T			Title - Contact		Phone - Conta	Phone - Contact*			Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance		NA	NA			Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative		Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance		NA NA			Product-Env-Stewards@onsemi.com				
Reque	ester Item Number	Mfr Item Number Mfr Item Name			Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type		
		NB7L86AMNI	HTBG SiGe Differential Level Select	Smart Gate with Output	2025-06-07		MY1	74.3	mg	Each		
<b>Ianufacturin</b>	g Proccess Informatio	n										
Termin	Terminal Plating / Grid Array Material Terminal Base Alloy		nal Base Alloy J	-STD-020 MSL Rating	SL Rating Peak Process Body Temperature Max Time at Pea			Temperature Number	er of Reflow Cy	cles		
Matte Tin (Sn) - annealed		CU All	CU Alloy 1		260 C 30		seconds 3					
omments												
vel 1 - maximun	n time at peak temperature	during soldering	g is 10-30 seconds									
or more informa	ation regarding material co	mposition please	e refer to page 3									

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such									
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.67	mg	Supplier	Silicon (Si)	7440-21-3		1.67	mg
Die Attach	0.37		Supplier	Silver (Ag)	7440-22-4		0.3145	mg
			Supplier	Acrylic resins	Proprietary Data		0.0555	mg
Lead Frame	33.6		Supplier	Silver (Ag)	7440-22-4		0.336	mg
			Supplier	Tin (Sn)	7440-31-5		0.084	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0739	mg
			Supplier	Chromium (Cr)	7440-47-3		0.084	mg
			Supplier	Copper (Cu)	7440-50-8		33.0221	mg
Mold Compound-Black	37.0			Epoxy resin	proprietary data		1.739	mg
			Supplier	Phenol Resin	Proprietary Data		1.739	mg
			Supplier	Carbon Black (C)	1333-86-4		0.037	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		33.485	mg
Plating	1.3	mg	Supplier	Tin (Sn)	7440-31-5		1.3	mg
Wire Bond - Au	0.36	mg	Supplier	Gold (Au)	7440-57-5		0.36	mg